

WHAT IS CLAIMED IS:

1. A electronic chip component comprising:
 - a chip including upper and lower surfaces, a pair of side surfaces, and first and second end surfaces facing each other;
 - a resonator electrode provided in the chip;
 - input and output electrodes extending in a vertical direction of the chip, which are coupled or connected to the resonator electrode; and
 - a first ground electrode disposed around the chip, the first ground electrode having a tubular shape so as to enclose the resonator electrode; wherein
 - the input and output electrodes are disposed at end portions or inner sides of the tubular first ground electrode, such that the input and output electrodes are not electrically connected to the first ground electrode; and
 - the electronic chip component further includes at least a pair of second ground electrodes which are disposed on both sides of at least one of the input electrode and the output electrode and which are electrically connected to the first ground electrode.
2. A electronic chip component according to Claim 1, wherein the chip is substantially rectangular, the input and output electrodes are disposed on the first and second end surfaces facing each other, respectively, and the first ground electrode includes surfaces that are substantially parallel to the upper and lower surfaces and the pair of side surfaces of the chip so as to define a tubular shape.
3. A electronic chip component according to Claim 2, wherein at least one of the surfaces of the first ground electrode that are substantially parallel to the upper and lower surfaces and the pair of side surfaces of the chip is embedded in the chip.

4. A electronic chip component according to Claim 2, wherein the first ground electrode surrounds the upper and lower surfaces and the pair of side surfaces of the chip.

5. A electronic chip component according to Claim 1, wherein the input and output electrodes extend in the vertical direction on the first and second end surfaces, respectively.

6. A electronic chip component according to Claim 2, wherein the input and output electrodes include via-hole electrodes which extend in the vertical direction in the chip and which are led to the upper or lower surface of the chip so as not to be electrically connected to the first ground electrode.

7. A electronic chip component according to Claim 2, wherein the second ground electrodes extend in the vertical direction at the end surfaces of the chip.

8. A electronic chip component according to Claim 2, wherein the second ground electrodes extend in the vertical direction in the chip and are electrically connected to the first ground electrode at at least one of the upper surface and the lower surface of the chip.

9. A electronic chip component according to Claim 1, wherein the resonator electrode is arranged so as to generate a plurality of resonance modes which are not degraded and the resonator electrode includes a through hole for coupling the plurality of resonance modes, whereby a band-pass filter is provided.

10. A electronic chip component according to Claim 9, further comprising a third ground electrode which extends in the through hole so as not to be in contact with the resonator electrode and which is electrically connected to the first ground electrode.

11. A electronic chip component according to Claim 1, wherein the resonator electrode comprises a ring-shaped resonator.